

Integrated Device Technology, Inc.

6024 Silver Creek Valley Road San Jose, CA 95138 USA

Manufacturing Bulletin

Subject: **QFN 11mm x11 mm (NQ/NQG 148) Tray Conversion**

Date: 15August 2011

This notification is to advise our customers that IDT has qualified a new shipping tray type for 11mm x 11mm QFN-148 package and will convert to the new shipping trays for shipment with effective from October 03, 2011.

There are changes in the tray pocket dimensions. However, there are no changes to tray outer dimensions and number of units per tray.

The new tray provides better protection against possible damage during transportation for customer shipments.

Refer to attachment I for new and old tray top view differences.

Tray Dimension:

Description		Existing Tray	New Tray
Tray C	Outer Dimension	135.9 x 322.6 mm	135.9 x 322.6 mm
LengthxV	Width		
Tray Po	ocket Dimension	11.23 x 11.23 x 1.40 mm	11.20 x 11.20 x 1.30 mm
Length x	Width x Depth		

Changes on New Tray:

Description	Reason for Change	
Pocket dimension	To ease the detection of double units inside tray pocket.	
	(refer to attachment II(a)	
Bottom tray pocket with 4	To prevent unit sticky problem due to ESD static. (refer	
humps	to attachment II(b))	

Yours sincerely,

LS Koay

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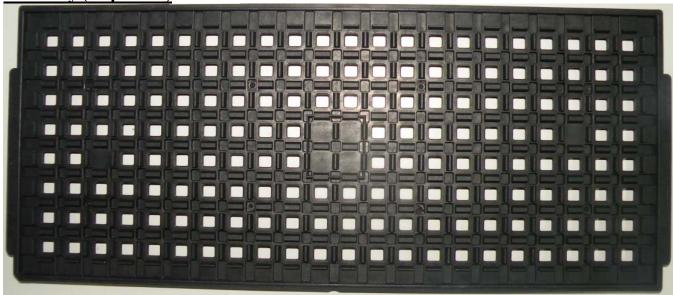
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Manufacturing Bulletin Attachment I

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Old Tray (Top View)



New Tray (Top View)





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Manufacturing Bulletin Attachment II

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New Tray (has gap if double units per pocket) (a)



New Tray (Bottom tray pocket with 4 humps) **(b)**

